

IN THE CLAIMS

Please cancel claims 1-12 and 22-30. Attached is a listing of the current claims.

13. (original) An electroless plating structure on a metal-six copper (M<sub>6</sub> Cu) pad, having a composition comprising:



wherein pM is a primary metal selected from at least one of Cu, Ag, Au, Co, Pd, Pt, Ni, Rh, and Ir;

wherein sM is a secondary metal selected from zero to at least one of Cr, Mo, W, Mn, Tc, and Re;

wherein B and P represent boron and phosphorus, respectively; and

wherein w has a range from about 0.5 to about 0.99, x has a range from about 0.0 to about 0.2, y has a range from about .01 to about 0.1, and z has a range from about 0.0 to about 0.02.

14. (original) The electroless plating structure according to claim 13 further including a metal compound selected from CuB, CuBP, CuCrB, CuCrBP, CuMoB, CuMoBP, CuWB, CuWBP, CuMnB, CuMnBP, CuTcB, CuTcBP, CuReB, CuReBP, CuNiB, CuNiBP, CuNiCrB, CuNiCrBP, CuNiMoB, CuNiMoBP, CuNiWB, CuNiWBP, CuNiMnB, CuNiMnBP, CuNiTcB, CuNiTcBP, CuNiReB, and CuNiReBP.

15. (original) The electroless plating structure according to claim 14, wherein Cu is substituted or accompanied by at least one of Ag and Au.

16. (original) The electroless plating structure according to claim 13 further including a metal compound selected from NiB, NiBP, NiCrB, NiCrBP, NiMoB, NiMoBP, NiWB, NiWBP, NiMnB, NiMnBP, NiTcB, NiTcBP, NiReB, NiReBP, NiCoB, NiCoBP, NiCoCrB, NiCoCrBP, NiCoMoB, NiCoMoBP, NiCoWB, NiCoWBP, NiCoMnB, NiCoMnBP, NiCoTcB, NiCoTcBP, NiCoReB, and NiCoReBP.

17. (original) The electroless plating structure according to claim 16, wherein Ni is substituted or accompanied by at least one of Pd and Pt.

18. (original) The electroless plating structure according to claim 13 further including a metal compound selected from CoB, CoBP, CoCrB, CoCrBP, CoMoB, CoMoBP, CoWB, CoWBP, CoMnB, CoMnBP, CoTcB, CoTcBP, CoReB, CoReBP, NiCoB, CoPdB, CoPdCrB, CoPdCrBP, CoPdMoB, CoPdMoBP, CoPdWB, CoPdWBP, CoPdMnB, CoPdMnBP, CoPdTcB, CoPdTcBP, CoPdReB, and CoPdReBP.

19. (original) The electroless plating structure according to claim 18, wherein Co is substituted or accompanied by at least one of Rh and Ir.

20. (original) The electroless plating structure according to claim 13, wherein the metal is a metal combination selected from cobalt-nickel, cobalt-nickel-silver, cobalt-

nickel-silver-copper, cobalt-silver, cobalt-silver-copper, cobalt-copper, cobalt-copper-nickel, nickel-silver, nickel-silver-copper, nickel-copper, and silver-copper.

21. (original) The electroless plating structure according to claim 13, wherein the metal is selected from MP, MB, MPB, MW, MWP, MWBP, MNiP, MNiWP, MReP, MReBP, and wherein M is a metal combination selected from cobalt-nickel, cobalt-nickel-silver, cobalt-nickel-silver-copper, cobalt-silver, cobalt-silver-copper, cobalt-copper, cobalt-copper-nickel, nickel-silver, nickel-silver-copper, nickel-copper, and silver-copper.